

IN THE CLAIMS

Please amend the claims as follows:

1.-37. (Canceled)

38. (Currently amended) A method of forming a display, comprising:

obtaining a substrate for use in the display; and

forming a plurality of pixel control circuits on the substrate, each pixel control circuit being configured to regulate ~~emission of~~ light from a pixel;

wherein forming the pixel control circuits includes depositing a semiconductor on the substrate from a solution.

39. (Original) The method of claim 38, wherein the semiconductor is an organic semiconductor.

40. (Original) The method of claim 39, wherein the semiconductor is selected from a group consisting of a polymer, a conjugated polymer and an oligomer.

41. (Original) The method of claim 39, wherein the semiconductor includes includes one or more polymers having a backbone with units selected from a group consisting of acetylenes, phenylenes, vinylenes, fluorines, thiophenes and cyclopentadithiophenes.

42. (Original) The method of claim 39, wherein the organic semiconductor includes MEH-PPV (poly(2-methoxy, 5 ethyl, (2' hexyloxy) para-phenylene vinylene).

43. (Original) The method of claim 39, wherein the organic semiconductor includes poly(3-hexyl-thiophene).

44. (Original) The method of claim 38, wherein the solution includes the semiconductor and a solvent.

45. (Original) The method of claim 38, wherein depositing the semiconductor on the substrate includes spin-coating, spray-coating or dip-coating.
46. (Original) The method of claim 38, wherein depositing the semiconductor on the substrate includes modifying one or more portions of the substrate such that the solution preferentially adheres to regions of the substrate.
47. (Original) The method of claim 46, wherein modifying one or more portions of the substrate includes increasing the hydrophobic nature of one or more portions of the substrate.
48. (Original) The method of claim 47, wherein modifying one or more portions of the substrate includes increasing the hydrophilic nature of one or more portions of the substrate.
49. (Original) The method of claim 38, further comprising:
 patterning the semiconductor deposited on the substrate.
50. (Original) The method of claim 38, wherein patterning the semiconductor includes using photolithography to pattern the semiconductor.
51. (Original) The method of claim 38, wherein depositing the semiconductor on the substrate includes printing the semiconductor on the substrate.
52. (Original) The method of claim 51, wherein printing the semiconductor on the substrate includes ink-jet printing, thermal transfer printing, silk-screen printing or offset printing.
53. (Original) The method of claim 51, wherein depositing the semiconductor on the substrate includes ink-jet printing.
54. (Original) The method of claim 38, wherein forming the circuits on the substrate includes forming electrodes on the substrate and depositing the semiconductor includes depositing at least a portion of the semiconductor over the electrodes.

55. (Original) The method of claim 38, wherein forming the circuits on the substrate includes forming one or more electrodes that include an organic conductor on the substrate.
56. (Original) The method of claim 38, wherein the substrate has a melting point less than 350 °C.
57. (Currently amended) A method of forming a display, comprising:
 obtaining a substrate for use in the display; and
 forming a plurality of pixel control circuits on a substrate, each pixel control circuit being configured to regulate ~~emission of~~ light from a pixel;
 wherein forming the pixel control circuits includes patterning an organic semiconductor on the substrate.
58. (Currently amended) A method of forming a display, comprising:
 obtaining a substrate for use in the display; and
 forming a plurality of pixel control circuits on the substrate, each pixel control circuit being configured to regulate ~~emission of~~ light from a pixel;
 wherein forming the pixel control circuits includes forming one or more electrodes that include an organic conductor on the substrate.
59. (Original) The method of claim 58, wherein the organic conductor is selected from a group consisting of polyaniline, polypyrrole, poly ethylene dioxythiophene.
60. (Original) The method of claim 58, wherein forming the one or more electrodes on the substrate includes depositing the organic conductor on the substrate from a solution.
61. (Original) The method of claim 60, wherein depositing the organic conductor on the substrate includes spin-coating, spray-coating or dip-coating.
62. (Original) The method of claim 60, further comprising:

patterning the organic conductor after depositing the organic conductor on the substrate.

63. (Original) The method of claim 62, wherein patterning the organic conductor includes using photolithography to pattern the semiconductor.

64. (Original) The method of claim 60, wherein depositing the organic conductor on the substrate includes patterning the semiconductor on the substrate.

65. (Original) The method of claim 60, wherein depositing the organic conductor on the substrate includes ink-jet printing, thermal transfer printing, silk-screen printing or offset printing.

66. (Original) The method of claim 60, wherein depositing the semiconductor on the substrate includes ink-jet printing.

67. (Original) The method of claim 58, wherein the substrate has a melting point less than 350 °C.

68. (Canceled)

69. (New) The method of claim 38, wherein the pixel control circuits are two-terminal circuits.

70. (New) The method of claim 38, further comprising:

including the substrate and pixel control circuits in a Micro-Electro-Mechanical Systems (MEMs) display, an organic light emitting diode (OLED) display, an electrochromic display, a Liquid Crystal Display, or an electrophoretic display.

71. (New) The method of claim 38, further comprising:

including the substrate and pixel control circuits in an image sensor array.

72. (New) The display of claim 57, wherein the semiconductor includes one or more components selected from a group consisting of a polymer, a conjugated polymer and an oligomer.

73. (New) The display of claim 57, wherein the semiconductor includes one or more polymers having a backbone with units selected from a group consisting of acetylenes, phenylenes, vinylenes, fluorines, thiophenes and cyclopentadithiophenes.

74. (New) The display of claim 57, wherein the organic semiconductor includes MEH-PPV (poly(2-methoxy, 5 ethyl, (2' hexyloxy) para-phenylene vinylene).

75. (New) The display of claim 57, wherein the organic semiconductor includes poly(3-hexyl-thiophene).